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1. Document ID: US 20030008516 A1

L9: Entry 1 of 16

File: PGPB

Jan 9, 2003

PGPUB-DOCUMENT-NUMBER: 20030008516

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20030008516 A1

TITLE: Method of reinforcing a low dielectric constant material layer against damage caused by a photoresist stripper

PUBLICATION-DATE: January 9, 2003

## INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Chang, Ting-Chang	Hsin-Chu City		TW	
Liu, Po-Tsun	Hsin-Chu City		TW	
Mor, Yi-Shien	Taipei City		TW	

US-CL-CURRENT: 438/704[Full](#) [Title](#) [Citation](#) [Front](#) [Review](#) [Classification](#) [Date](#) [Reference](#) [Sequences](#) [Attachments](#) [Claims](#) [KMC](#)  
[Draw Desc](#) [Image](#)

2. Document ID: US 20020164877 A1

L9: Entry 2 of 16

File: PGPB

Nov 7, 2002

PGPUB-DOCUMENT-NUMBER: 20020164877

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020164877 A1

TITLE: Process for forming metal-filled openings in low dielectric constant dielectric material while inhibiting via poisoning

PUBLICATION-DATE: November 7, 2002

## INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Catabay, Wilbur G.	Saratoga	CA	US	
Hsia, Wei-Jen	Sunnyvale	CA	US	
Lu, Hong-Qiang	Fremont	CA	US	
Kim, Yong-Bae	Cupertino	CA	US	
Kumar, Kiran	Sunnyvale	CA	US	
Zhang, Kai	Saratoga	CA	US	
Schinella, Richard	Saratoga	CA	US	
Schoenborn, Philippe	San Mateo	CA	US	

US-CL-CURRENT: 438/694

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3. Document ID: US 20020058397 A1

L9: Entry 3 of 16

File: PGPB

May 16, 2002

PGPUB-DOCUMENT-NUMBER: 20020058397

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020058397 A1

TITLE: Hydrogen plasma photoresist strip and polymeric residue cleanup process for low dielectric constant materials

PUBLICATION-DATE: May 16, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Smith, Patricia B.	Colleyville	TX	US	
Eissa, Mona M.	Plano	TX	US	

US-CL-CURRENT: 438/475

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4. Document ID: US 20020028575 A1

L9: Entry 4 of 16

File: PGPB

Mar 7, 2002

PGPUB-DOCUMENT-NUMBER: 20020028575

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020028575 A1

TITLE: Method of manufacturing a semiconductor device

PUBLICATION-DATE: March 7, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Besling, Willem Frederik Adrianus	Eindhoven		NL	
Mutsaers, Cornelis Adrianus Henricus Antonius	Eindhoven		NL	
Gravesteijn, Dirk Jan	Eindhoven		NL	

US-CL-CURRENT: 438/638; 438/639, 438/640

<a href="#">Full</a>	<a href="#">Title</a>	<a href="#">Citation</a>	<a href="#">Front</a>	<a href="#">Review</a>	<a href="#">Classification</a>	<a href="#">Date</a>	<a href="#">Reference</a>	<a href="#">Sequences</a>	<a href="#">Attachments</a>	<a href="#">Claims</a>	<a href="#">KMC</a>
<a href="#">Draw</a>	<a href="#">Desc</a>	<a href="#">Image</a>									

5. Document ID: US 20020020053 A1

L9: Entry 5 of 16

File: PGPB

Feb 21, 2002

PGPUB-DOCUMENT-NUMBER: 20020020053

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20020020053 A1

TITLE: Deposited thin films and their use in separation and sacrificial layer applications

PUBLICATION-DATE: February 21, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Fonash, Stephen J.	State College	PA	US	
Nam, Wook Jun	State College	PA	US	
Lee, Youngchul	State College	PA	US	
Chang, Kyuhwan	State College	PA	US	
Hayes, Daniel J.	State College	PA	US	
Kalkan, A. Kaan	State College	PA	US	
Bae, Sanghoon	Cupertino	CA	US	

US-CL-CURRENT: 29/623.1; 156/249, 204/192.12, 216/17, 216/36, 216/40, 427/2.1, 427/96, 430/256, 430/314, 430/320, 438/149, 438/49, 438/64

<a href="#">Full</a>	<a href="#">Title</a>	<a href="#">Citation</a>	<a href="#">Front</a>	<a href="#">Review</a>	<a href="#">Classification</a>	<a href="#">Date</a>	<a href="#">Reference</a>	<a href="#">Sequences</a>	<a href="#">Attachments</a>	<a href="#">KMC</a>
<a href="#">Draw</a>	<a href="#">Desc</a>	<a href="#">Image</a>								

6. Document ID: US 20010027016 A1

L9: Entry 6 of 16

File: PGPB

Oct 4, 2001

PGPUB-DOCUMENT-NUMBER: 20010027016

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20010027016 A1

TITLE: Oxygen free plasma stripping process

PUBLICATION-DATE: October 4, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Han, Qingyan	Columbia	MD	US	
Berry, Ivan	Ellicott City	MD	US	
Sakthivel, Palani	Gaithersburg	MD	US	
Ruffin, Ricky	Gaithersburg	MD	US	
Dahimene, Mahmoud	Sunnyvale	CA	US	

US-CL-CURRENT: 438/689

<a href="#">Full</a>	<a href="#">Title</a>	<a href="#">Citation</a>	<a href="#">Front</a>	<a href="#">Review</a>	<a href="#">Classification</a>	<a href="#">Date</a>	<a href="#">Reference</a>	<a href="#">Sequences</a>	<a href="#">Attachments</a>	<a href="#" style="border: 2px solid black; padding: 2px;">KMC</a>	
<a href="#">Draw</a>	<a href="#">Desc</a>	<a href="#">Image</a>									

7. Document ID: US 6528426 B1

L9: Entry 7 of 16

File: USPT

Mar 4, 2003

US-PAT-NO: 6528426

DOCUMENT-IDENTIFIER: US 6528426 B1

TITLE: Integrated circuit interconnect and method

DATE-ISSUED: March 4, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Olsen; Leif C.	Plano	TX		
Swanson; Leland S.	McKinney	TX		

US-CL-CURRENT: 438/689; 438/694, 438/700

<a href="#">Full</a>	<a href="#">Title</a>	<a href="#">Citation</a>	<a href="#">Front</a>	<a href="#">Review</a>	<a href="#">Classification</a>	<a href="#">Date</a>	<a href="#">Reference</a>	<a href="#">Sequences</a>	<a href="#">Attachments</a>	<a href="#" style="border: 2px solid black; padding: 2px;">KMC</a>	
<a href="#">Draw</a>	<a href="#">Desc</a>	<a href="#">Image</a>									

8. Document ID: US 6521547 B1

L9: Entry 8 of 16

File: USPT

Feb 18, 2003

US-PAT-NO: 6521547

DOCUMENT-IDENTIFIER: US 6521547 B1

TITLE: Method of repairing a low dielectric constant material layer

DATE-ISSUED: February 18, 2003

## INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Chang; Ting-Chang	Hsin-Chu			TW
Liu; Po-Tsun	Hsin-Chu			TW
Mor; Yi-Shien	Taipei			TW

US-CL-CURRENT: 438/781; 438/706

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 9. Document ID: US 6503840 B2

L9: Entry 9 of 16

File: USPT

Jan 7, 2003

US-PAT-NO: 6503840

DOCUMENT-IDENTIFIER: US 6503840 B2

TITLE: Process for forming metal-filled openings in low dielectric constant dielectric material while inhibiting via poisoning

DATE-ISSUED: January 7, 2003

## INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Catabay; Wilbur G.	Saratoga	CA		
Hsia; Wei-Jen	Sunnyvale	CA		
Lu; Hong-Qiang	Fremont	CA		
Kim; Yong-Bae	Cupertino	CA		
Kumar; Kiran	Sunnyvale	CA		
Zhang; Kai	Saratoga	CA		
Schinella; Richard	Saratoga	CA		
Schoenborn; Philippe	San Mateo	CA		

US-CL-CURRENT: 438/694; 257/E21.252, 438/699, 438/700, 438/702, 438/709, 438/718, 438/725

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 10. Document ID: US 6444136 B1

L9: Entry 10 of 16

File: USPT

Sep 3, 2002

US-PAT-NO: 6444136

DOCUMENT-IDENTIFIER: US 6444136 B1

TITLE: Fabrication of improved low-k dielectric structures

DATE-ISSUED: September 3, 2002

## **INVENTOR-INFORMATION:**

NAME	CITY	STATE	ZIP CODE	COUNTRY
Liu; Q. Z.	Irvine	CA		
Zhao; Bin	Irvine	CA		

US-CL-CURRENT: 216/62; 216/17, 216/18, 216/67, 438/637, 438/725

□ 11. Document ID: US 6406640 B1

L9: Entry 11 of 16

File: USPT

Jun 18, 2002

US-PAT-NO: 6406640

DOCUMENT-IDENTIFIER: US 6406640 B1

## TITLE: Plasma etching method

DATE-ISSUED: June 18, 2002

## **INVENTOR-INFORMATION:**

NAME	CITY	STATE	ZIP CODE	COUNTRY
Yang; Chan-Ion	Los Gatos	CA		
Raghuram; Usha	San Jose	CA		
Kaufman; Kimberley A.	Eden Prairie	MN		
Arnzen; Daniel	Eden Prairie	MN		
Nulty; James	San Jose	CA		

US-CL-CURRENT: 216/67; 216/79, 216/80, 438/710, 438/714, 438/723

12. Document ID: US 6323121 B1

L9: Entry 12 of 16

File: USPT

Nov 27, 2001

US-PAT-NO: 6323121

DOCUMENT-IDENTIFIER: US 6323121 B1

## TITLE: Fully dry post-via-etch cleaning method for a damascene process

DATE-ISSUED: November 27, 2001

**INVENTOR-INFORMATION:**

NAME	CITY	STATE	ZIP CODE	COUNTRY
Liu; Jen-Cheng	Chia-Yi			TW
Chen; Chao-Cheng	Matou			TW
Chao; Li-Chih	Yang-Mei			TW
Tsai; Chia-Shiung	Hsin-Chu			TW
Lui; Ming-Huei	Panchiao			TW

US-CL-CURRENT: [438/633](#); [430/314](#), [430/329](#), [430/330](#), [438/597](#), [438/738](#)

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13. Document ID: US 6316354 B1

L9: Entry 13 of 16

File: USPT

Nov 13, 2001

US-PAT-NO: 6316354

DOCUMENT-IDENTIFIER: US 6316354 B1

TITLE: Process for removing resist mask of integrated circuit structure which mitigates damage to underlying low dielectric constant silicon oxide dielectric layer

DATE-ISSUED: November 13, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Hu; John Rongxiang	Sunnyvale	CA		

US-CL-CURRENT: [438/652](#); [438/624](#), [438/634](#)

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14. Document ID: US 6281135 B1

L9: Entry 14 of 16

File: USPT

Aug 28, 2001

US-PAT-NO: 6281135

DOCUMENT-IDENTIFIER: US 6281135 B1

TITLE: Oxygen free plasma stripping process

DATE-ISSUED: August 28, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Han; Qingyuan	Columbia	MD		
Berry; Ivan	Ellicot City	MD		
Sakthivel; Palani	Gaithersburg	MD		
Ruffin; Ricky	Gaithersburg	MD		
Dahimene; Mammoud	Gaithersburg	MD		

US-CL-CURRENT: [438/725](#); [438/963](#)

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15. Document ID: US 6204192 B1

L9: Entry 15 of 16

File: USPT

Mar 20, 2001

US-PAT-NO: 6204192

DOCUMENT-IDENTIFIER: US 6204192 B1

TITLE: Plasma cleaning process for openings formed in at least one low dielectric constant insulation layer over copper metallization in integrated circuit structures

DATE-ISSUED: March 20, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Zhao; Joe W.	San Jose	CA		
Hsia; Wei-Jen	Sunnyvale	CA		
Catabay; Wilbur G.	Saratoga	CA		

US-CL-CURRENT: [438/723](#); [134/1.2](#), [216/18](#), [216/67](#), [438/743](#)

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Term	Documents
LOW.DWPI,TDBD,EPAB,JPAB,USPT,PGPB.	3137987
LOWS.DWPI,TDBD,EPAB,JPAB,USPT,PGPB.	2106
K.DWPI,TDBD,EPAB,JPAB,USPT,PGPB.	1595050
KS.DWPI,TDBD,EPAB,JPAB,USPT,PGPB.	23217
(8 AND (LOW ADJ K)).USPT,PGPB,JPAB,EPAB,DWPI,TDBD.	16
(L8 AND (LOW K)).USPT,PGPB,JPAB,EPAB,DWPI,TDBD.	16

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